

Fabrication of interdigital transducers and growth of ZnO films for the generation of surface acoustic waves

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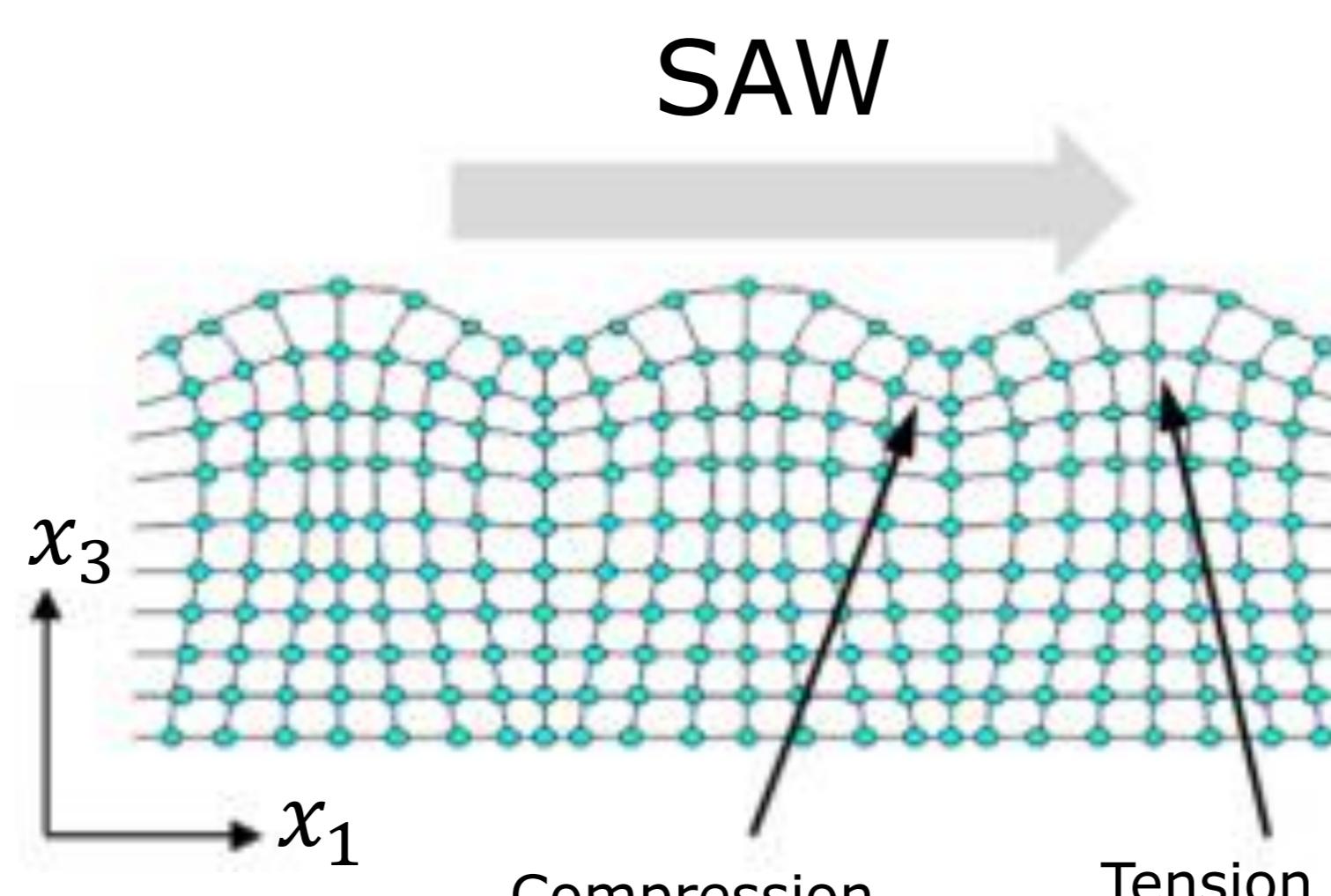


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Motivation

Surface acoustic waves (SAWs)

- ✓ High strain and piezoelectric fields
- ✓ Non-destructive tool
- ✓ Probing of interactions in semiconductor nanostructures
- ✓ High acousto-optical modulation
- ✓ Industry applications
- ✓ Filtering, sensing, signal processing



ZnO Films

- ✓ High piezoelectric material
- ✓ Generation of SAWs in non-piezoelectric substrates

Simulation

SAW generation

- ✓ Finite Element Method (FEM)

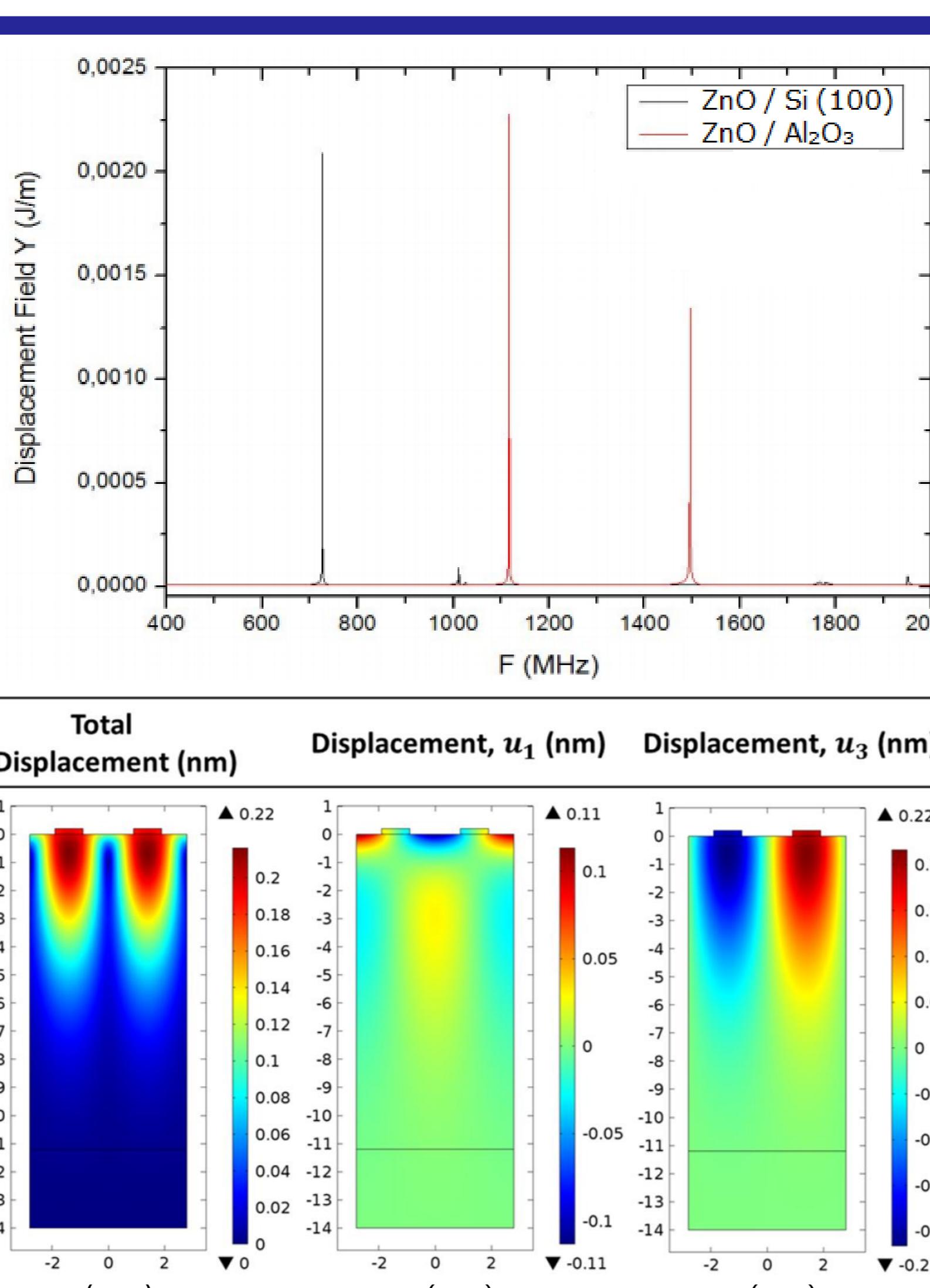
Material	Geometry	Thickness (μm)
Air	Top cover	0.3
Aluminium	IDTs	0.2
ZnO	Substrate	14.0

Boundary Conditions

Electric Potential	$V = V_{RF}$
Ground	$V = 0$
Fixed Constraint	$ u = 0$
Periodic Condition (continuity)	$\phi_L = \phi_R$ $u_L = u_R$
Free	$T = 0$

Substrate:

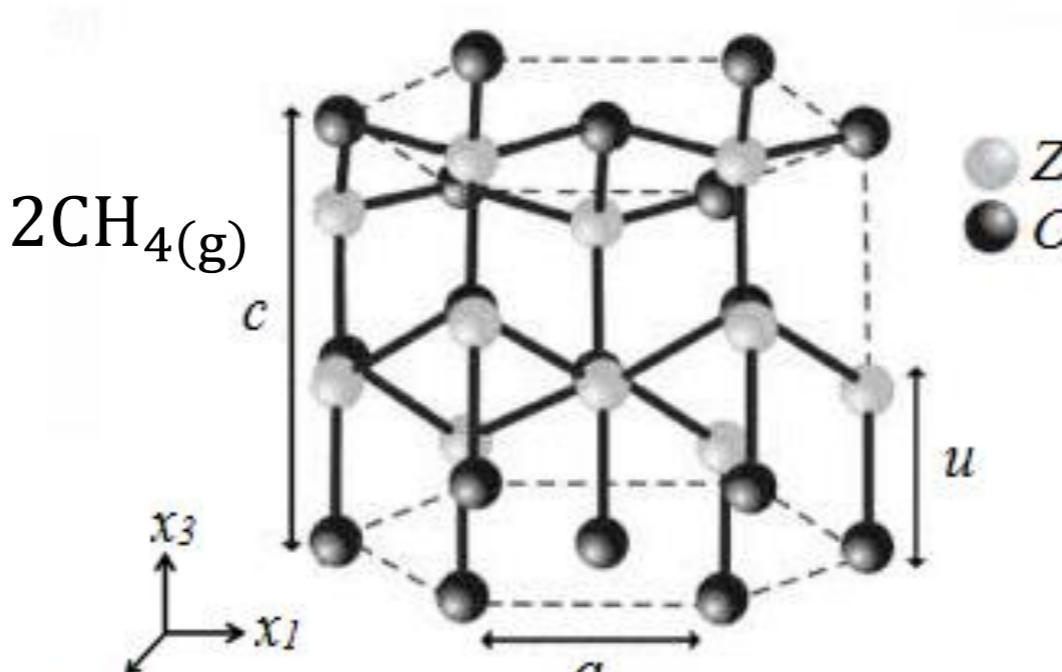
- ✓ Sapphire (Al_2O_3) and Si (111)
- ✓ 500 nm ZnO thin film
- ✓ c-oriented
- ✓ Calculation of SAW resonances
- ✓ $\lambda_{SAW} = 5.6 \mu\text{m}$
- ✓ Mode visualization



Growth of ZnO thin films

Process

- ✓ Atomic Layer Deposition (ALD): $\text{Zn}(\text{CH}_3)_2 + \text{H}_2\text{O} \rightarrow \text{ZnO} + 2\text{CH}_4(g)$
- ✓ Substrates: sapphire (Al_2O_3), Si (111) and Si (100)



Substrate	Temp [°C]	T ₁ [s]	T ₂ [s]	T ₃ [s]	T ₄ [s]
Si (100)	150	0,15	0,15	0,50	0,75
Si (111)	150	0,15	0,15	0,50	0,75
Al_2O_3	150	0,15	0,15	10,00	20,00
Si (111)	150	0,15	0,15	10,00	20,00
Al_2O_3	180	0,15	0,15	10,00	20,00
Si (111)	180	0,15	0,15	10,00	20,00
Al_2O_3	210	0,15	0,15	10,00	20,00
Si (111)	210	0,15	0,15	10,00	20,00
Al_2O_3	240	0,15	0,15	10,00	20,00
Si (111)	240	0,15	0,15	10,00	20,00

Photoluminescence (PL)

- ✓ ZnO on Si (111) at RT

✓ PL homogeneously along film's directions

✓ E_g in good agreement with literature reports [1]

✓ Relatively low defect density

✓ Same results obtained for Si (100) and (111)

X-Ray Diffraction (XRD)

- ✓ Optimized for c-oriented films (piezoelectricity)

✓ 150°C

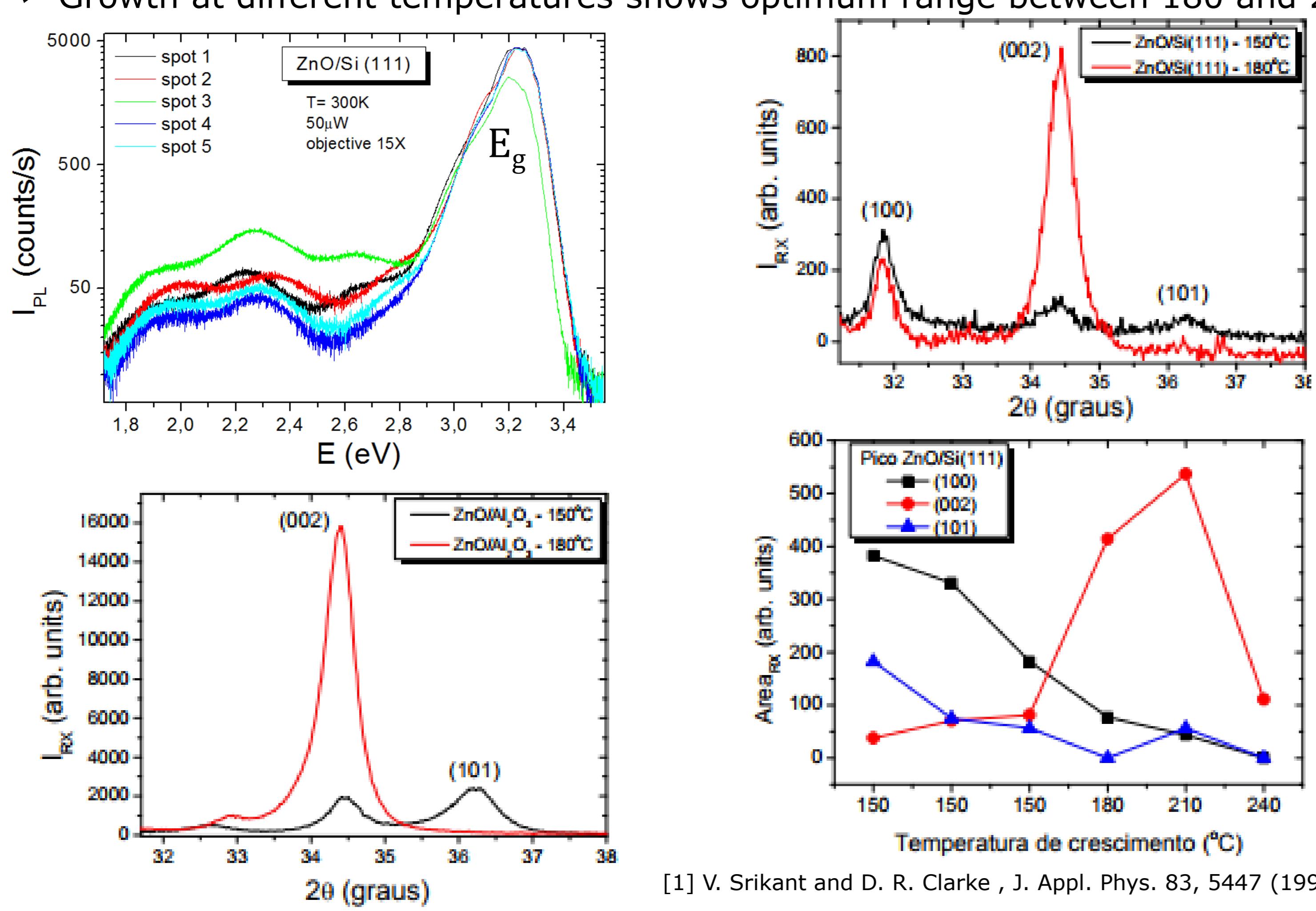
✓ (100), (002) and (101) diffraction peaks detected

✓ (002) peak weak in comparison with (100) and (101)

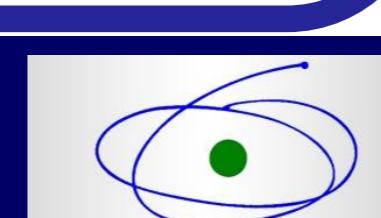
✓ 180°C

✓ (002) peak dominates (100) and (101)

✓ Growth at different temperatures shows optimum range between 180 and 210°C



Acknowledgments



Transducer fabrication

Interdigital transducers (IDTs)

Mask Generation

- ✓ Mask: 96 IDTs (48 pairs)

✓ Geometry

✓ Single Finger (SF)

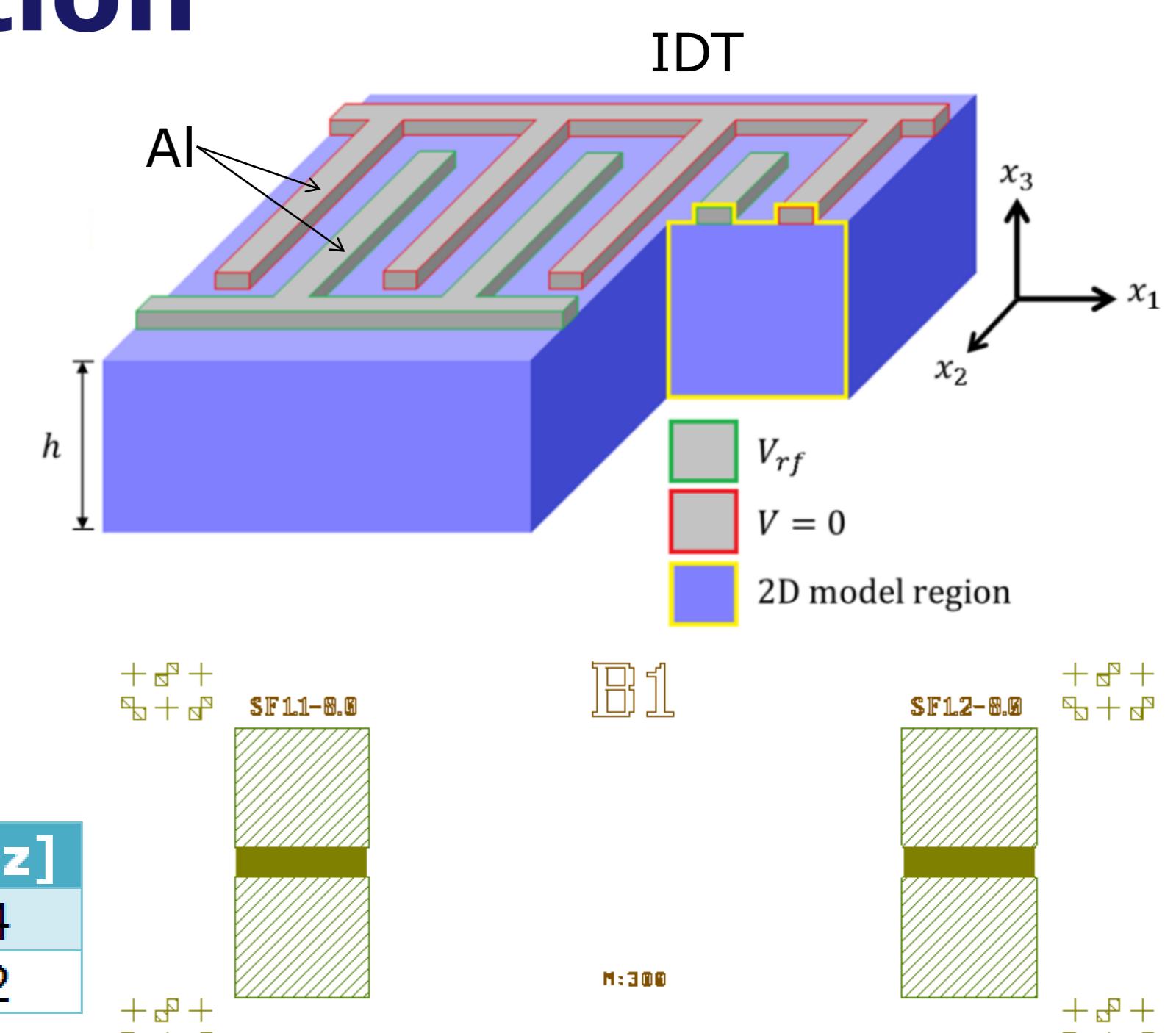
✓ Double Finger (DF)

Parameters

✓ $\lambda_{SAW} = 8 \mu\text{m}$ and $16 \mu\text{m}$

✓ $v_{SAW} = \lambda_{SAW} f_{SAW}$

Material	$v [\text{m}\cdot\text{s}^{-1}]$	$f_1 [\text{MHz}]$	$f_2 [\text{MHz}]$
ZnO	2694	336.8	168.4
LiNbO ₃	3843	480.4	240.2



Process

✓ Optical Lithography

✓ Aluminum metallization

✓ Lift-off

✓ Tests

✓ Substrate: Si

✓ E-beam resist: 200 nm thickness

✓ Particles due to resist aging

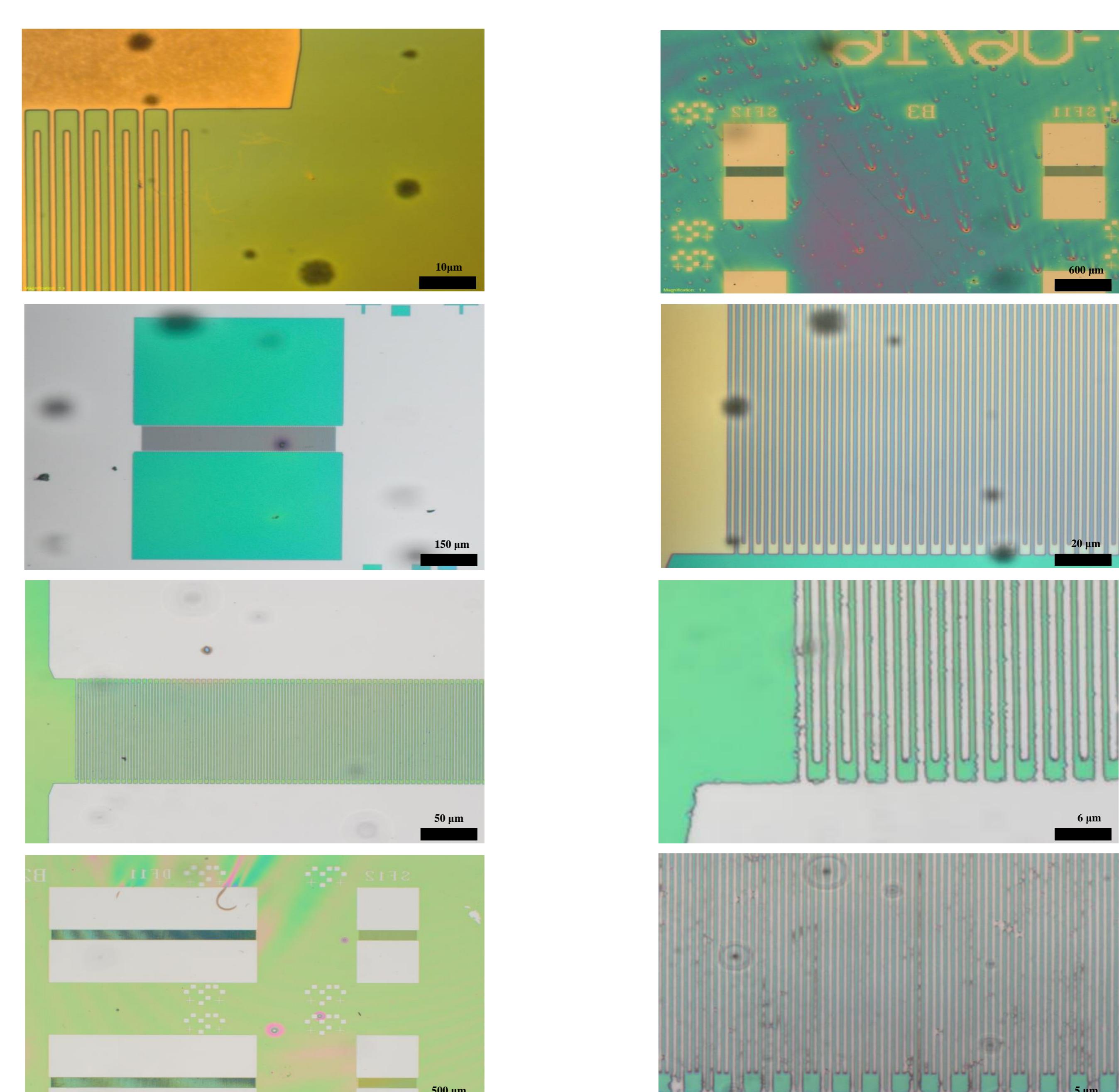
✓ Photo resist: AZ-5206

✓ Conditions:

✓ Inversion photolithography

✓ Parameters to be optimized

✓ exposition time, hard bake temperature, revelation time



Conclusions

ZnO Growth

✓ Atomic layer deposition

✓ c-oriented films

✓ Optimum temperature range: 180 – 200°C

✓ Long growth times

✓ Reduction needed more complex layered structures

Fabrication

✓ Metal fingers

✓ Well defined, better on single finger geometry

✓ Double finger width larger than system resolution

✓ Inversion Photolithography: functional process

✓ New tests needed for optimization and reproducibility

[1] V. Srikant and D. R. Clarke , J. Appl. Phys. 83, 5447 (1998).

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